

MOXLIE RISER 4

<3 SLOT- WITH 48 LANES>

STAGE: PVT
VERSION: 3.10
DATE: 2018.11.23
PCB P/N: PCB-3RSMOXL8-P0

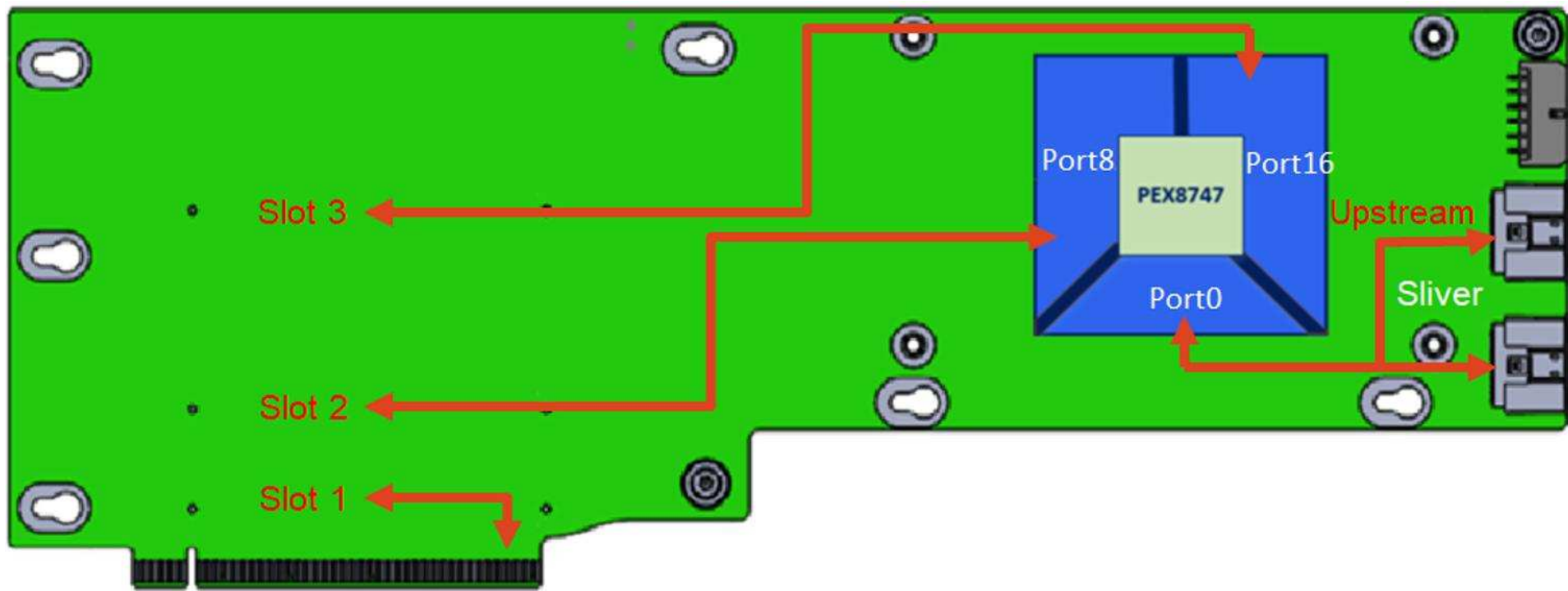


DEPARTMENT	DESIGNER	NAME	PROJECT				DOCUMENT NUMBER				REV
	REVIEWER	NAME	<ZT_PROJ>				<ZT_NUMBER>				<ZT_REV>
			SIZE	C	DATE	Fri Nov 23 13:37:38 2018	SHEET 1 OF 44				

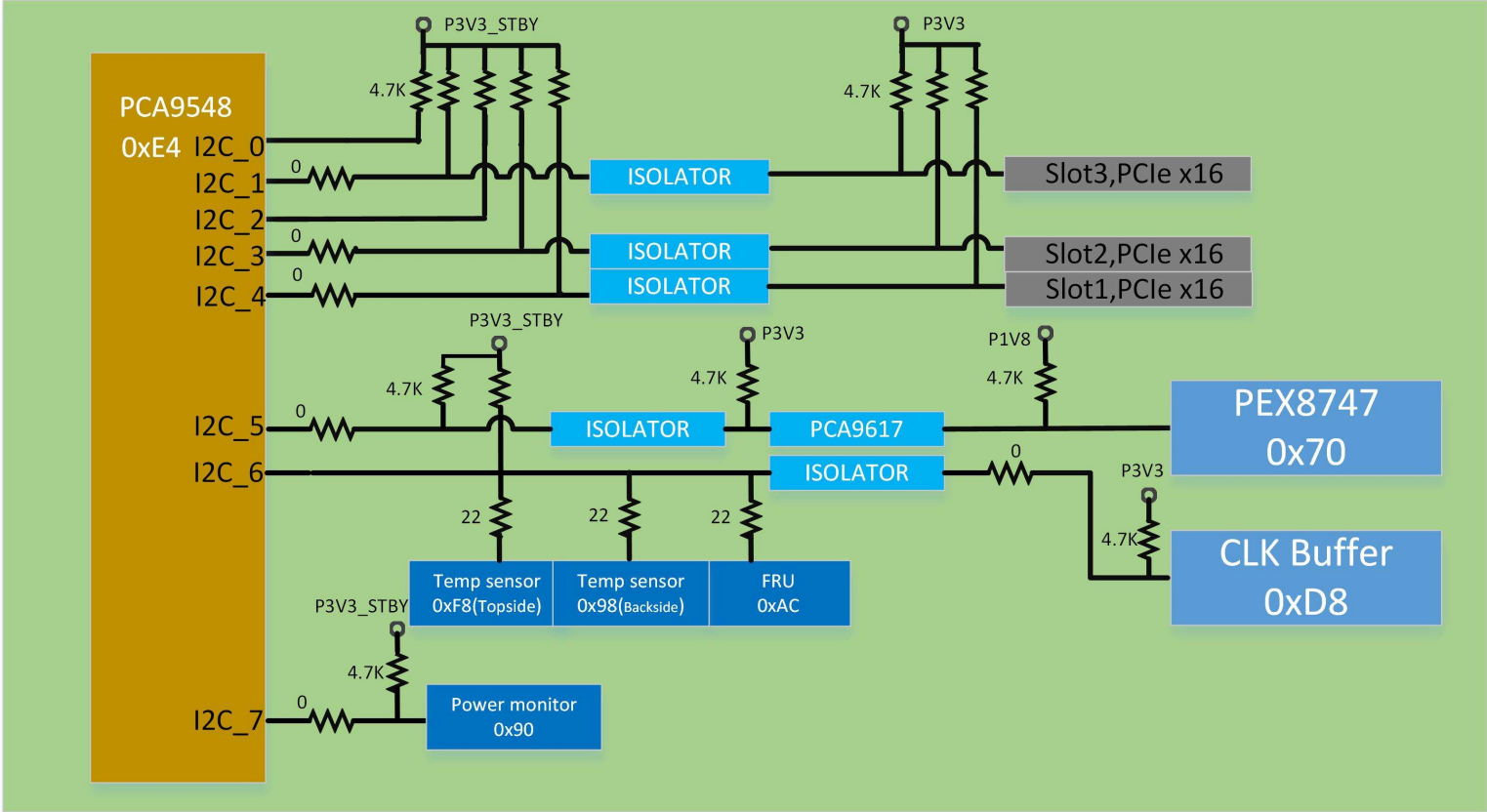
Layer			Dielectric and Copper Properties						Layer		
			Copper		Dielectric Material			Actual Dk	Actual Df/1MHz	Design	Actual
Name	Description	Type	Weight	Type	Type	Er	Df			Thickness (mil)	Thickness (mil)
Top_SM	Top Soldermask	Soldermask			Soldermask	3.5	0.030	3.70		0.50	
L1top	Signal_L1top	Signal	0.5 oz. plated	STD						1.90	
PP_L1top_L2	Prepreg	PP			1080*1	3.6	0.009	3.50	0.007	2.70	
L2	GND_L2	GND	1.0 oz.	RTF						1.30	
Core_L2_L3	Core	Core			2116	3.6	0.009	3.50	0.007	4.00	
L3	Signal_L3	Signal	1.0 oz.	RTF						1.30	
PP_L3_L4	Prepreg	PP			2116*3	3.6	0.009	3.50	0.007	15.00	
L4	PWR_L4	PWR	2.0 oz.	RTF						2.60	
Core_L4_L5	Core	Core			2116X1	3.8	0.009	3.60	0.007	4.00	
L5	PWR_L5	PWR	2.0 oz.	RTF						2.60	
PP_L5_L6	Prepreg	PP			2116*3	3.6	0.009	3.50	0.007	15.00	
L6	Signal_L6	Signal	1.0 oz.	RTF						1.30	
Core_L6_L7	Core	Core			2116	3.6	0.009	3.50	0.007	4.00	
L7	GND_L7	GND	1.0 oz.	RTF						1.30	
PP_L7_L8bot	Prepreg	PP			1080*1	3.6	0.009	3.50	0.007	2.70	
L8bot	Signal_L8bot	Signal	0.5 oz. plated	STD						1.90	
Bot_SM	Bot Soldermask	Soldermask			Soldermask	3.5	0.030	3.70		0.50	

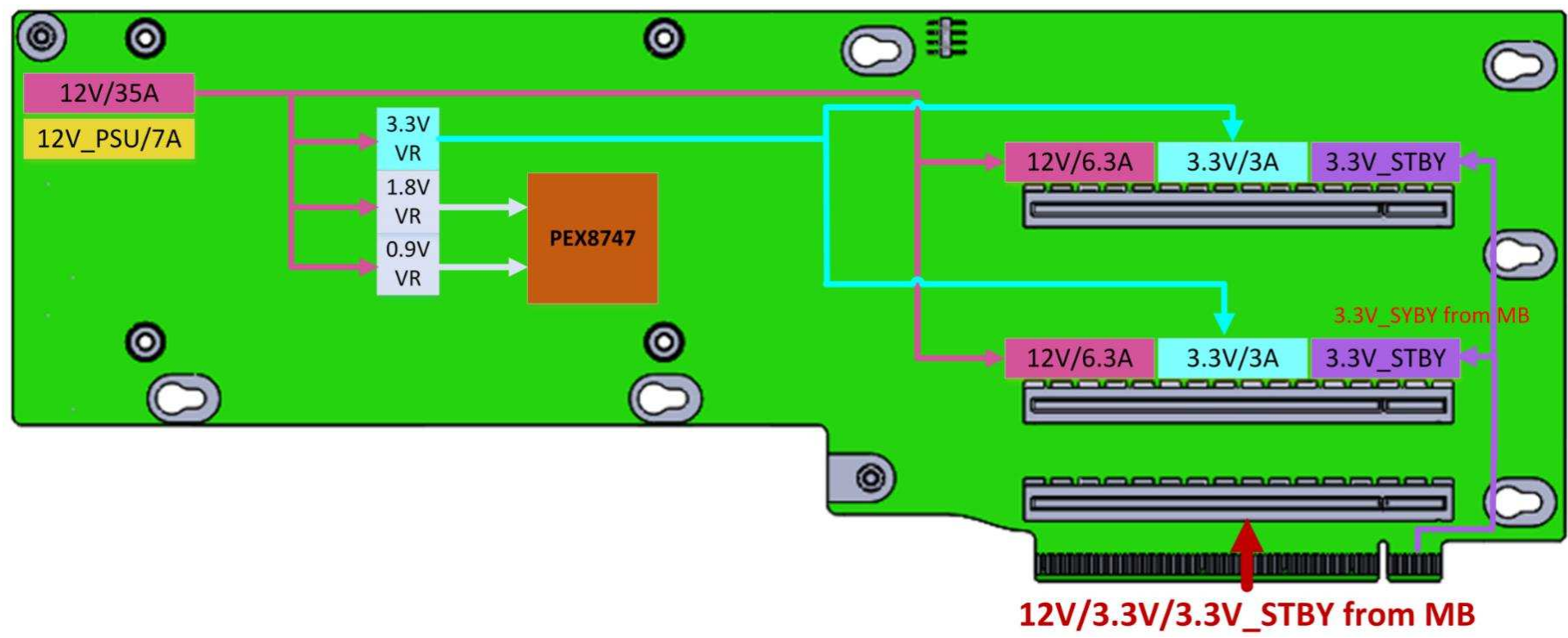
with soldermask, total thickness: 62.60 0.00
without soldermask, total thickness: 61.60 0.00



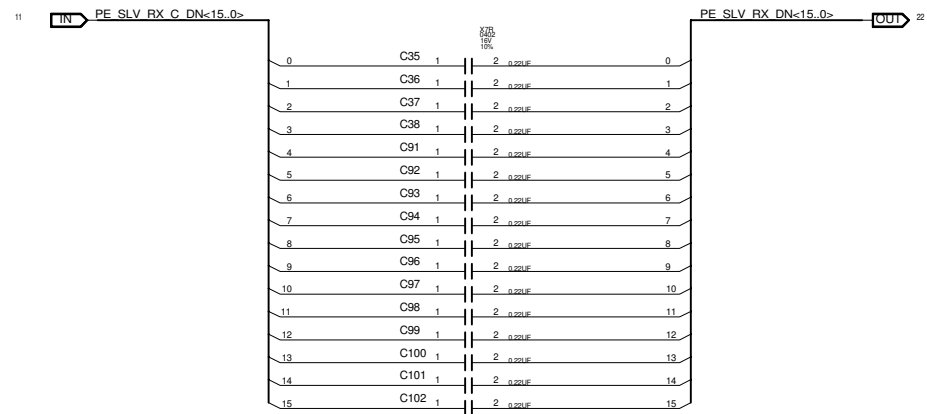
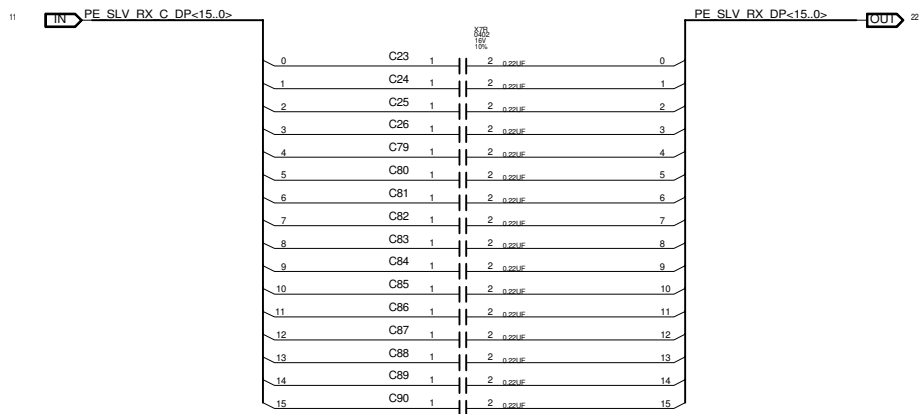
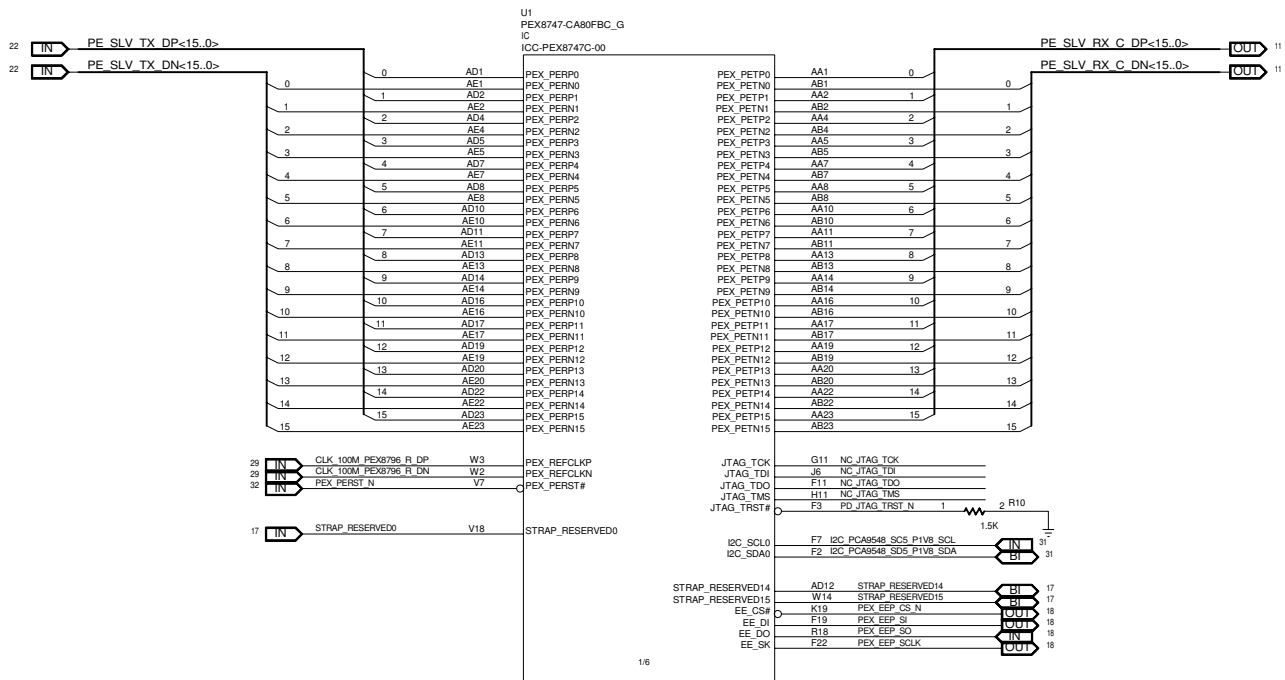


PEX8747	PORTS	SLOTS	NUMBER
	PORT 0	UPSTREAM(FROM	SLIVER CONN)
	PORT 8	SLOT	2
	PORT 16	SLOT	3

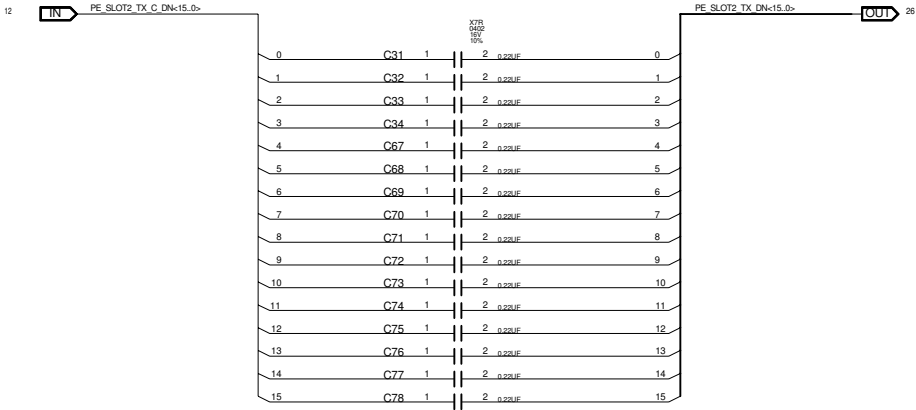
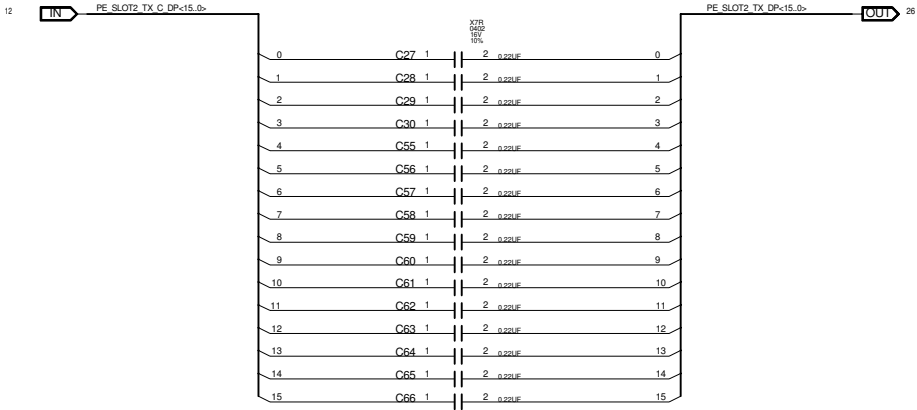
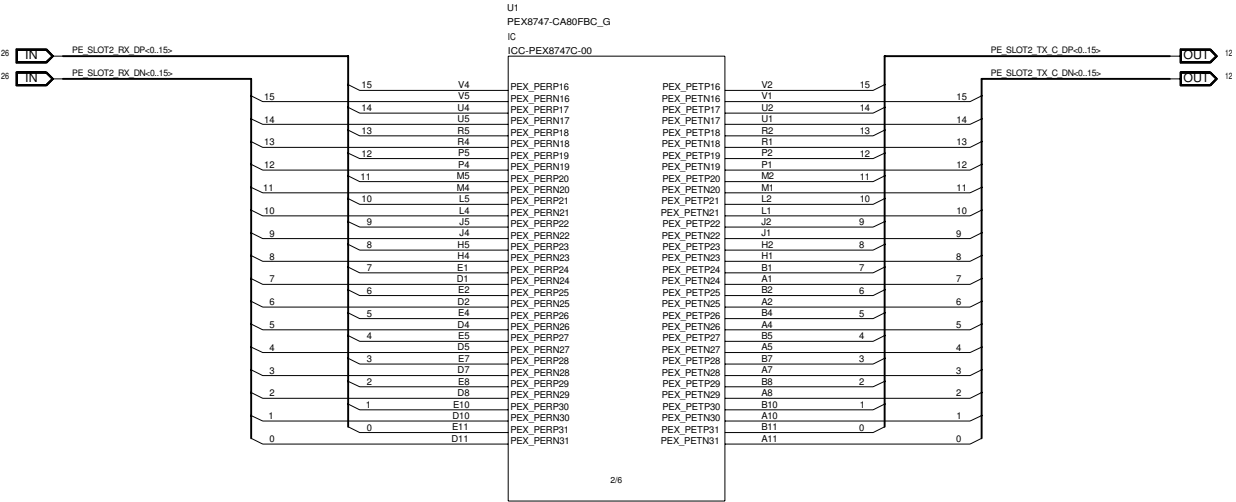




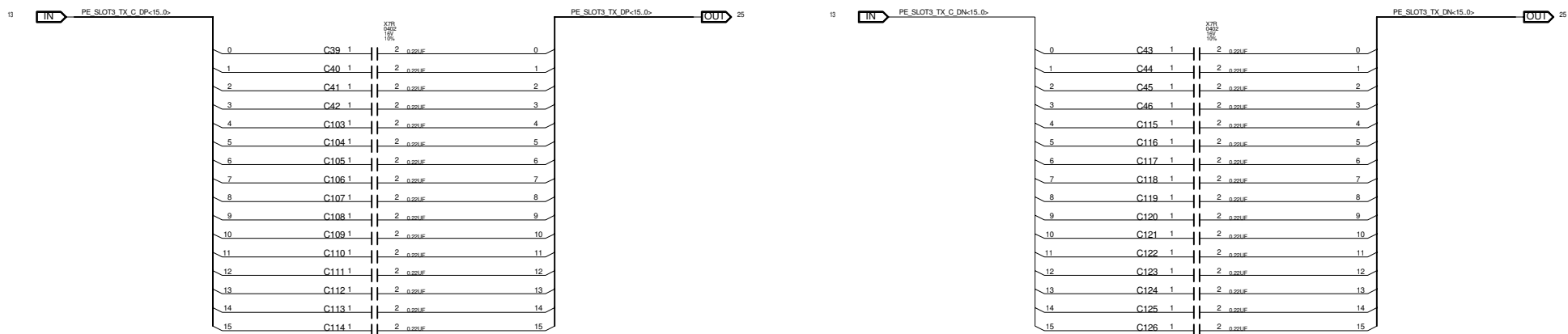
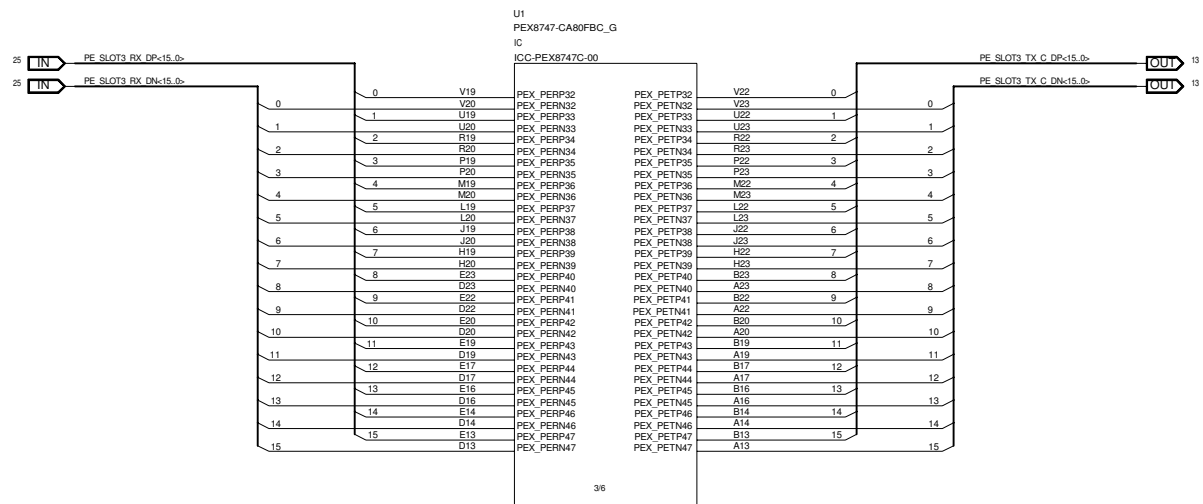
PEX8747 PORT0(0~15)

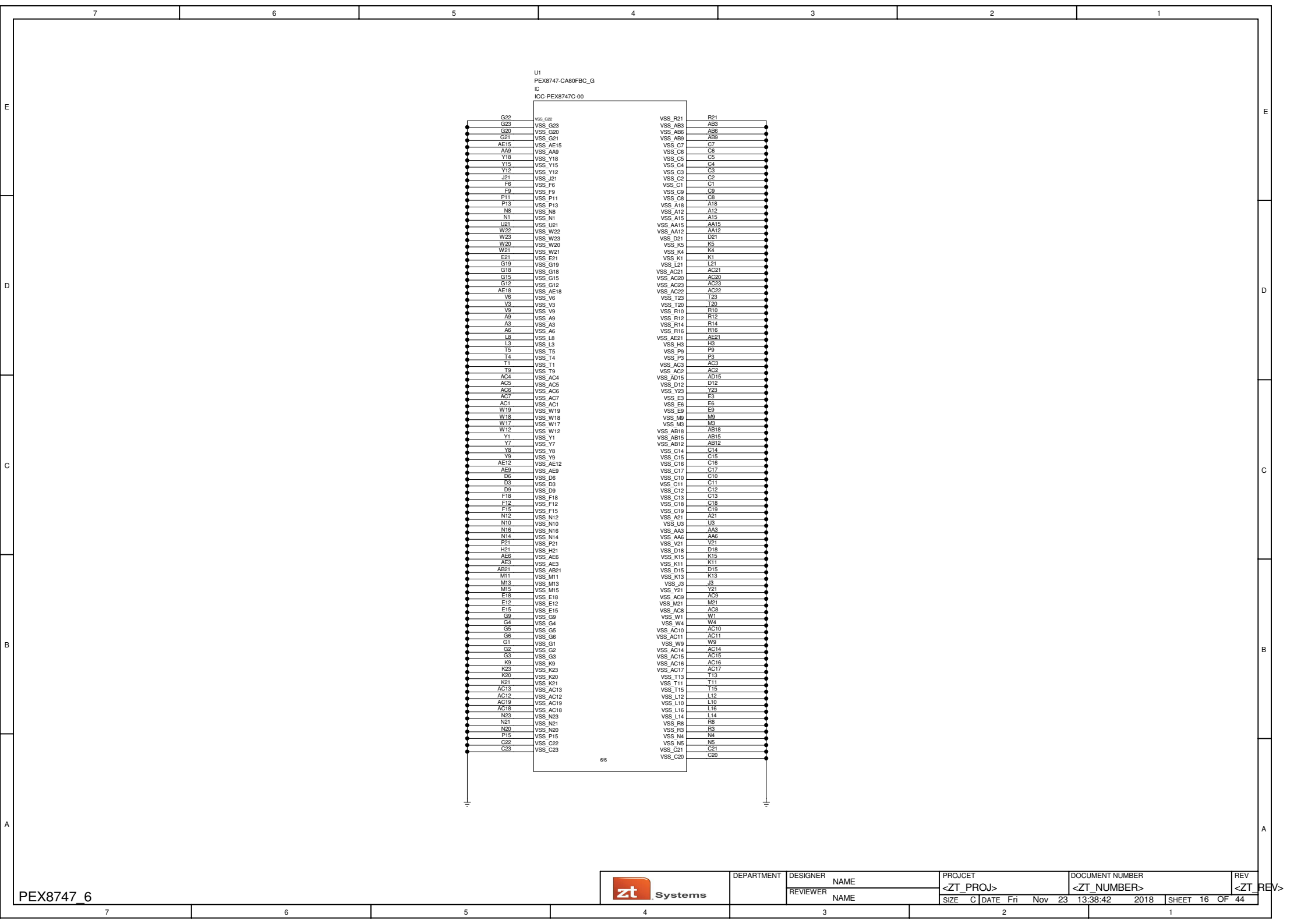


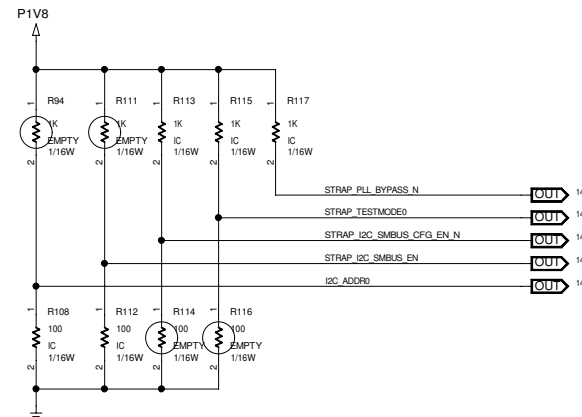
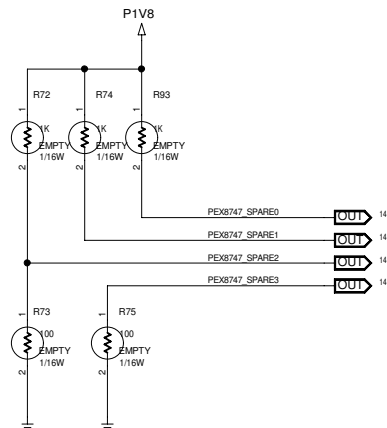
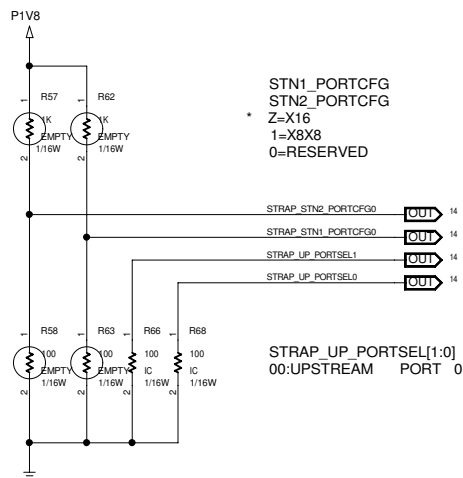
PEX8747 PORT8(16~31)



PEX8747 PORT16(32~47)







The three possible default I²C Slave/SMBus Device Address values are listed below.

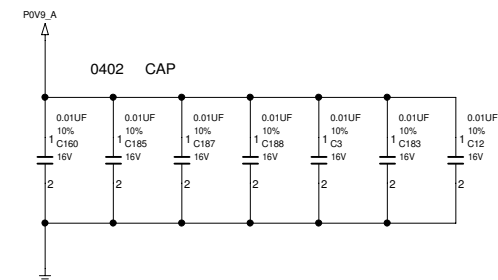
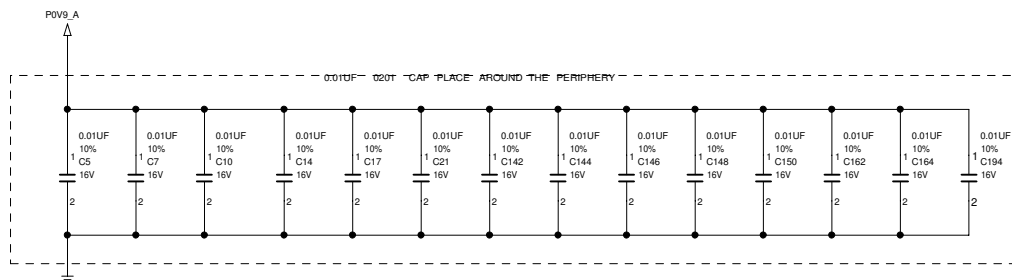
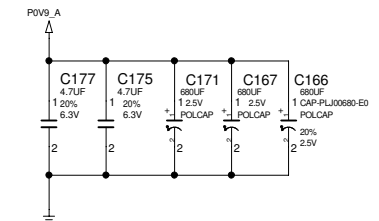
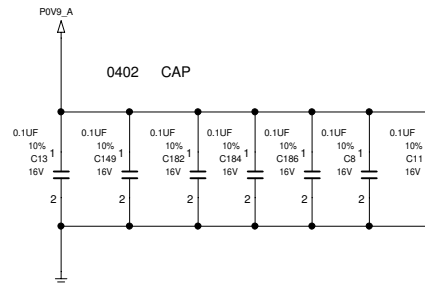
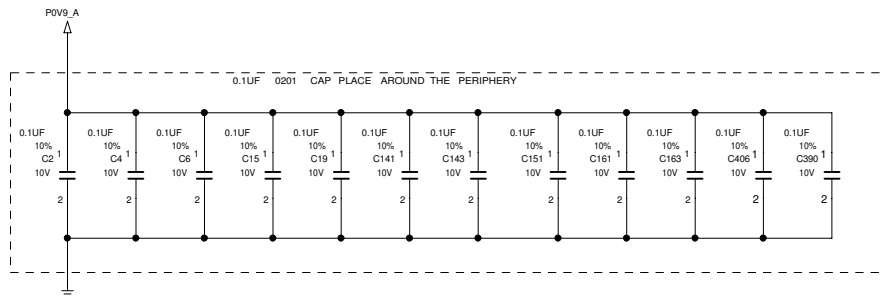
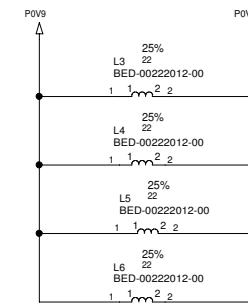
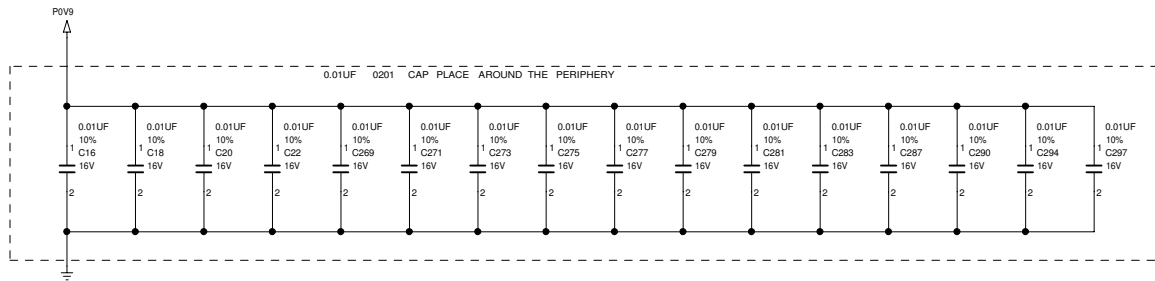
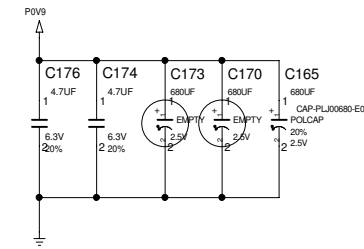
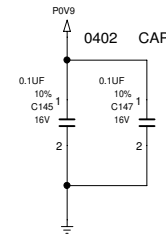
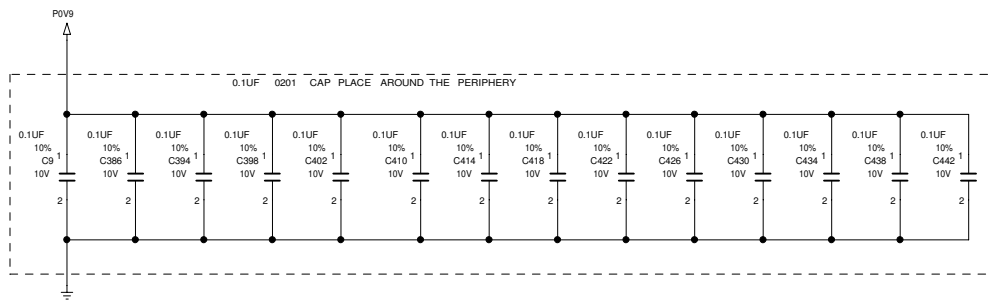
I2C_ADDR0 Input State	I ² C Slave/SMBus Device Address
0	0111_000b (default)
Z	0111_001b
1	0111_010b

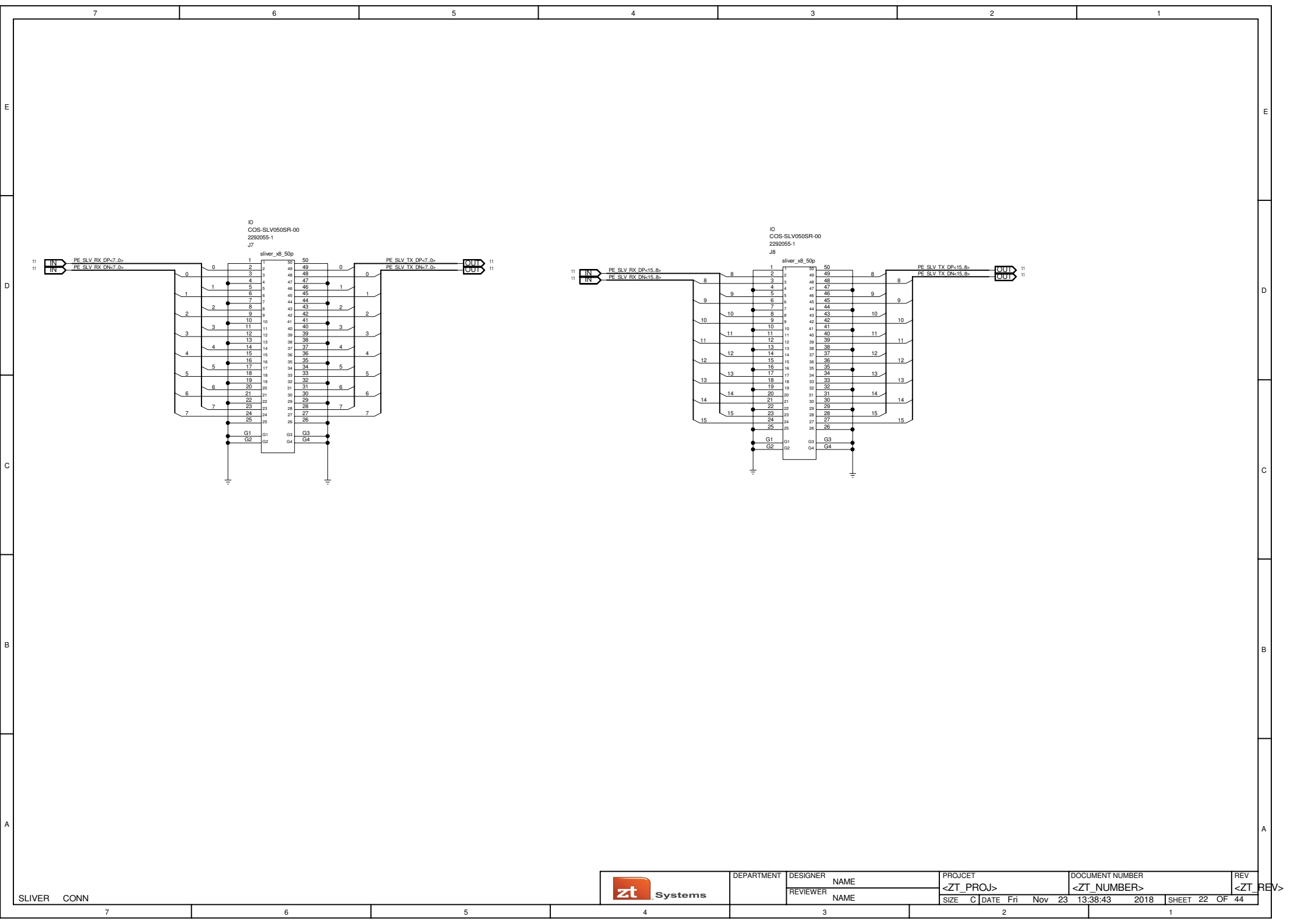
STRAP_I2C_SMBUS_EN:
 * 0= ENABLE I2C SLAVE PROTOCOL ON I2C_SCL0 AND I2C_SDA0 2-WIRE BUS
 Z,1= ENABLE SMBUS WITHOUT ARP, ON THE I2C_SCL0 AND I2C_SDA0 2-WIRE BUS

STRAP_I2C_SMBUS_CFG_EN_N:
 0= ENABLE I2C/SMBUS FOR INITIAL DEVICE CONFIGURATION
 * 1= DISABLE I2C/SMBUS FOR INITIAL DEVICE CONFIGURATION

STRAP_TESTMODE0:
 0= PORT_GOOD[9:8, 5:4, 0]# FUNCTIONALITY DEFAULTS TO PORT_GOOD FOR PORTS 17, 16, 9, 8 AND 0
 Z= FACTORY TEST ONLY
 * 1= PORT_GOOD[9:8, 5:4, 0]# AND GPIO[10, 7:6, 3:1] FUNCTIONALITY DEFAULTS TO GPIO INPUT







E

E

D

D

C

C

B

B

A

A

UNTITLED



DEPARTMENT

DESIGNER

NAME _____

PROJCET

<ZT_PROJ>

DOCUMENT NUMBER

<ZT_NUMBER>

REV

REV>

REVIEWER

NAME

SIZE	C
------	---

C	D
---	---

C	DATE
---	------

The Test

ue Ju

31

17:40

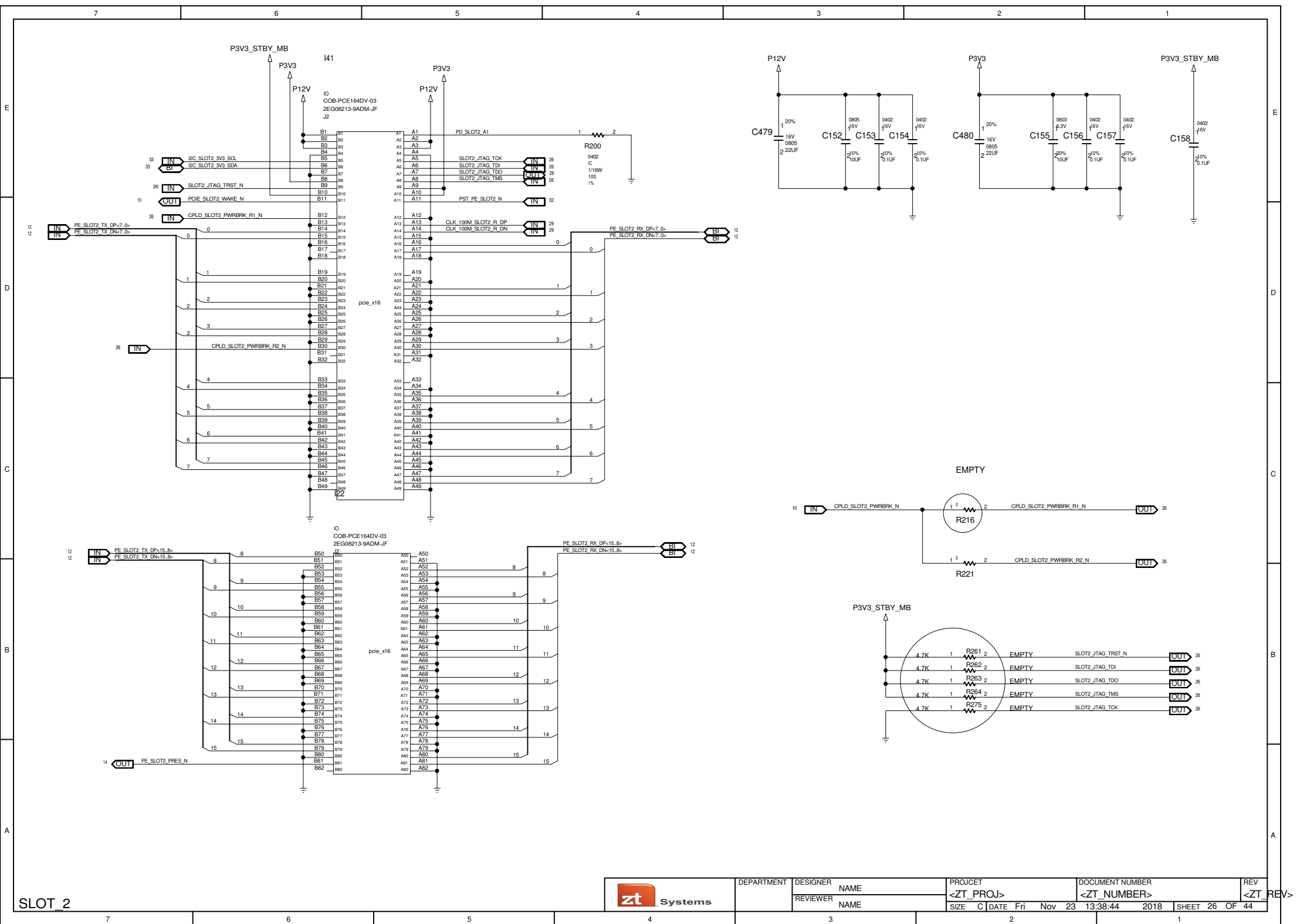
0:38

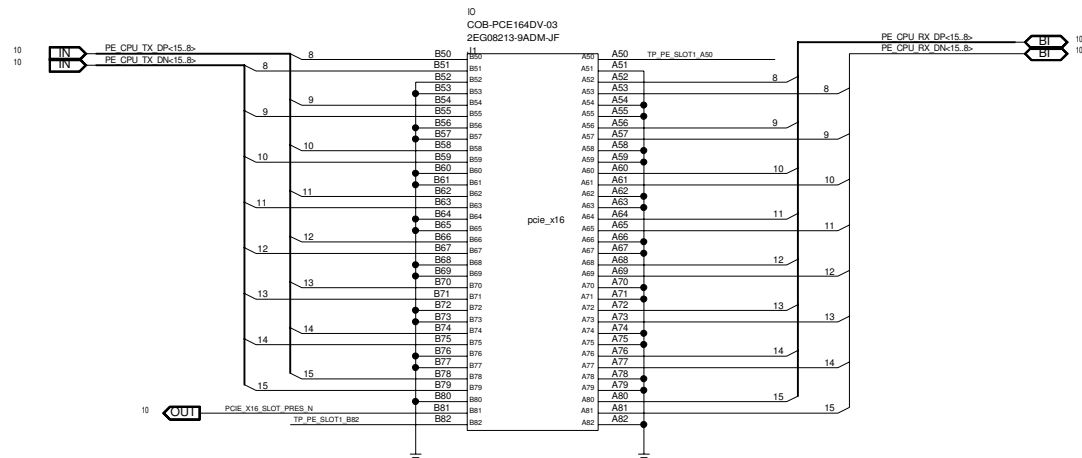
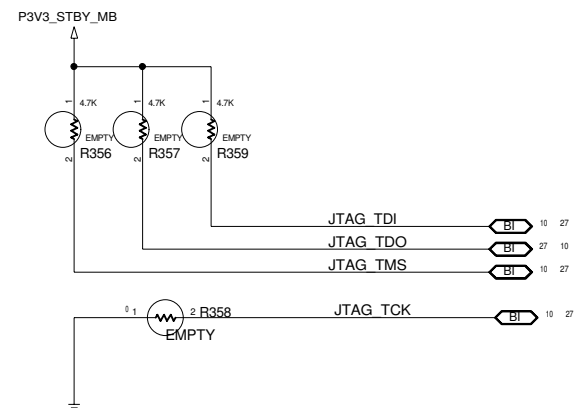
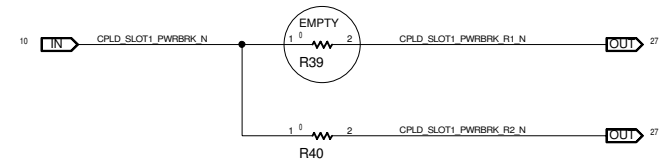
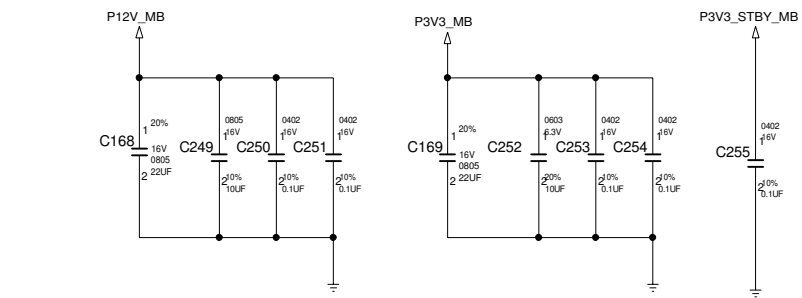
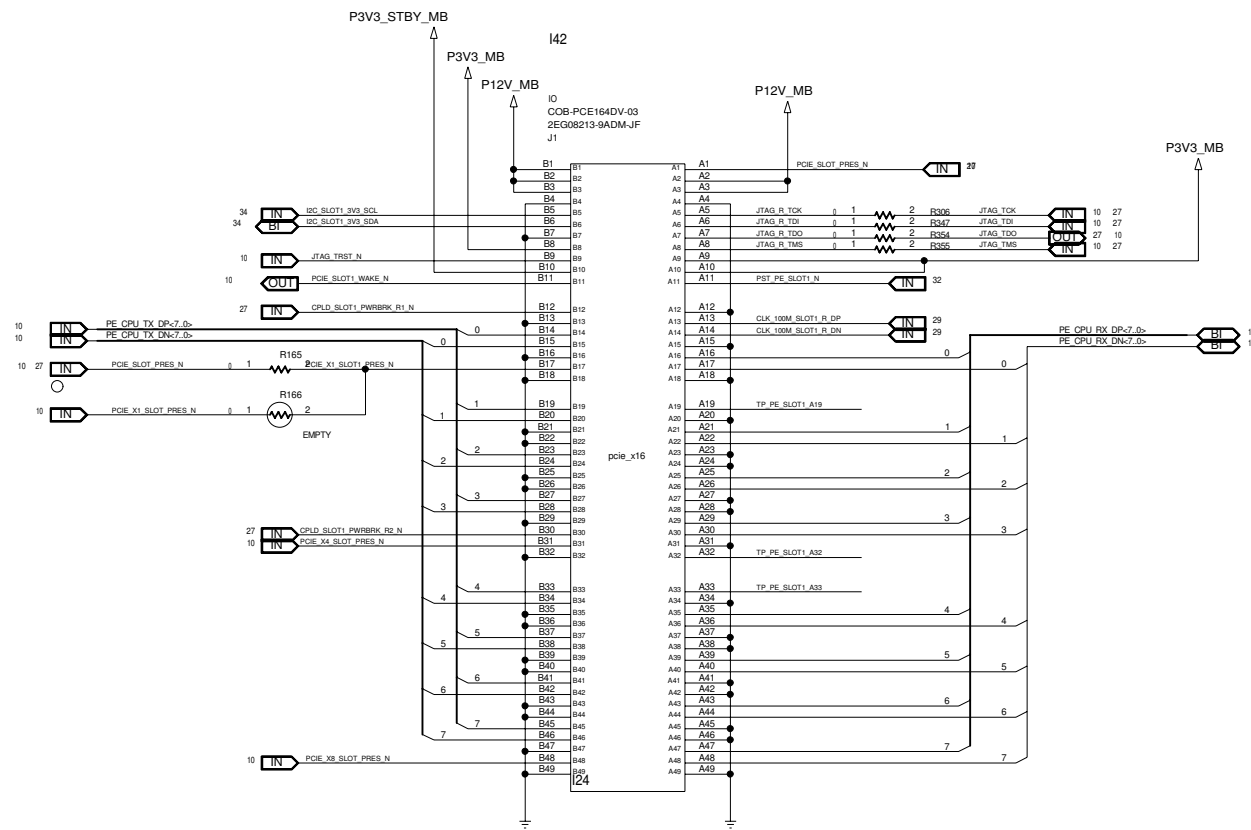
2018

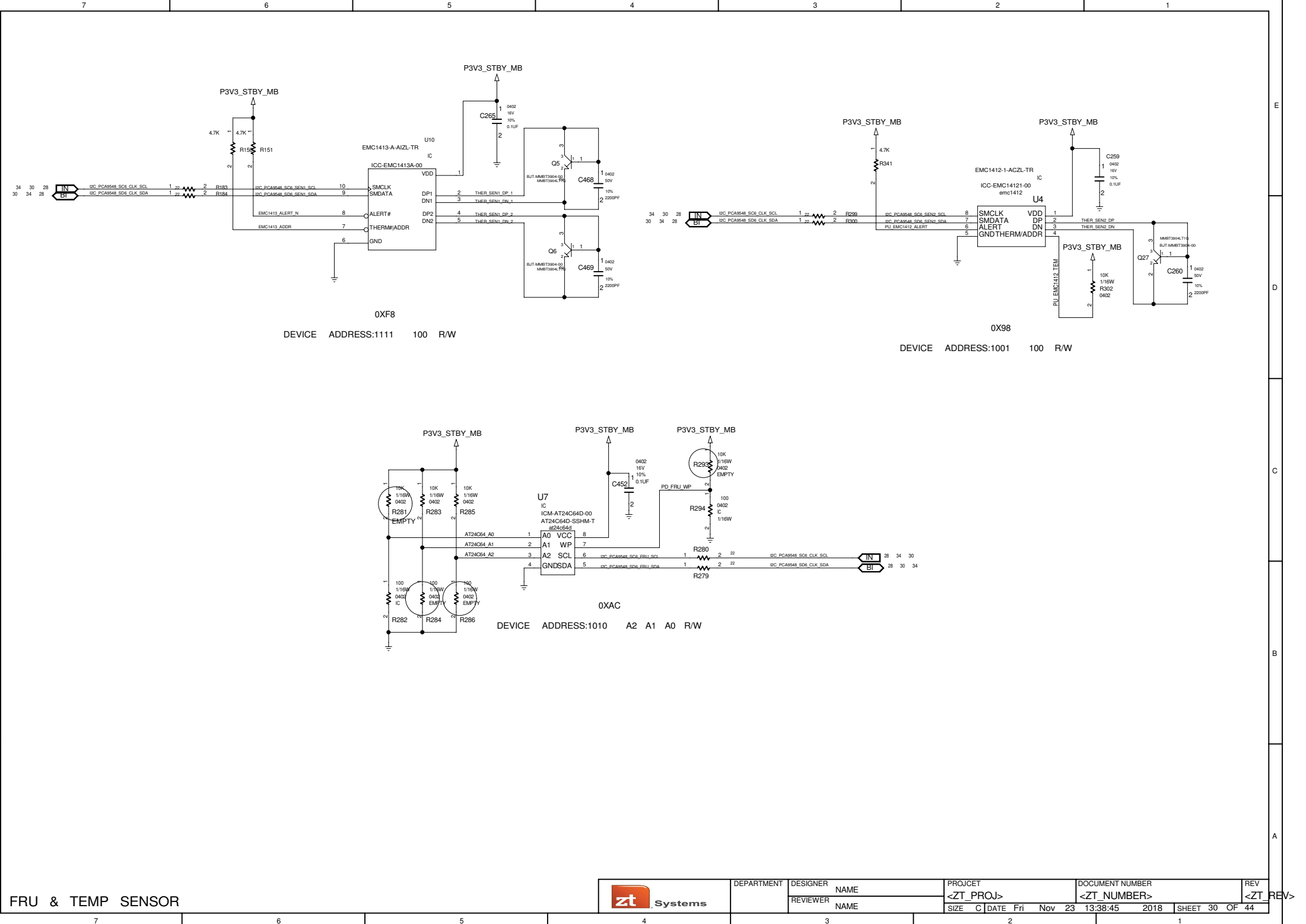
3	SH
---	----

EET 24

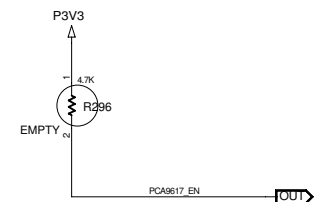
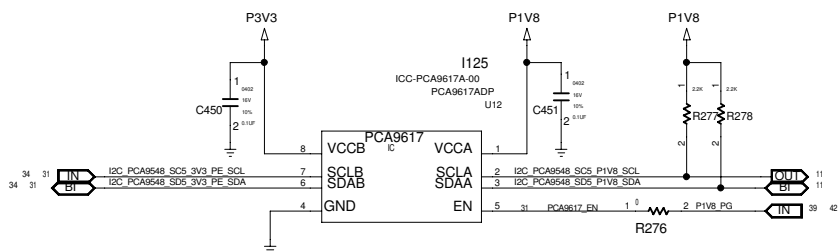
4 OF



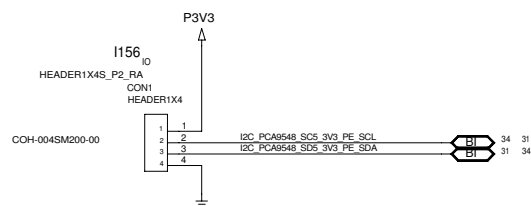


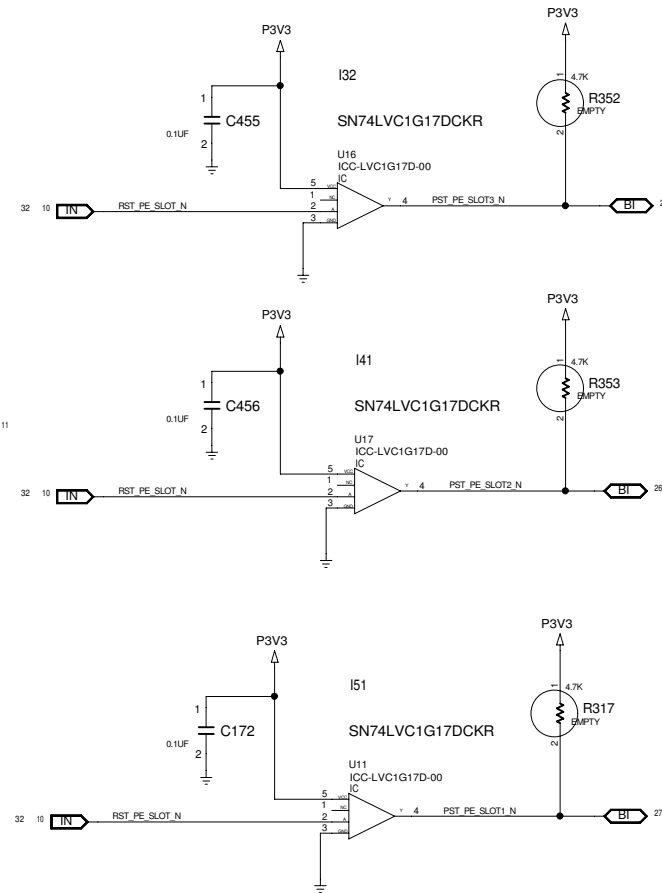
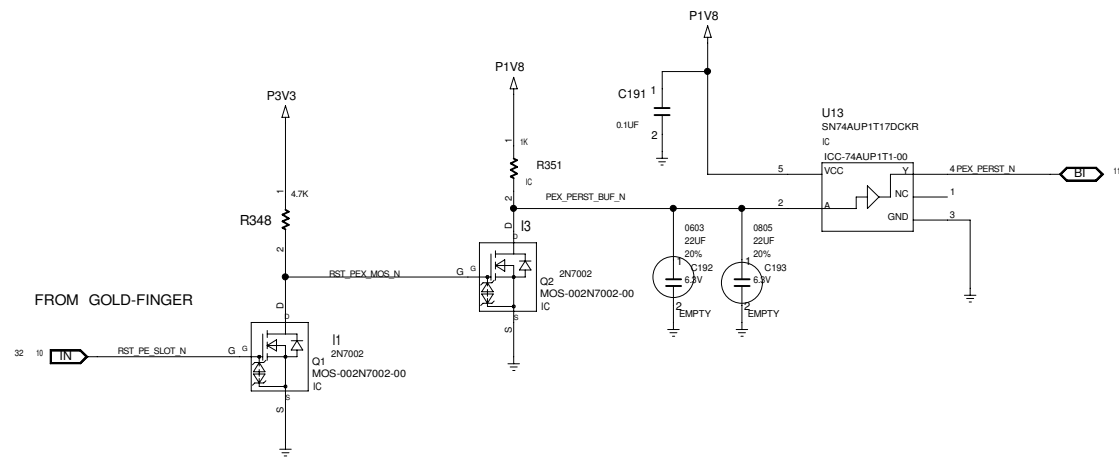


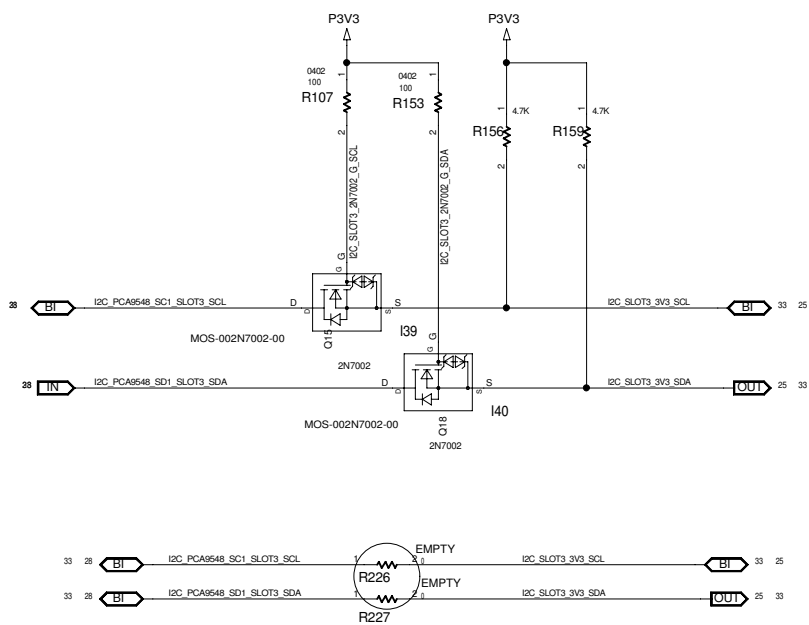
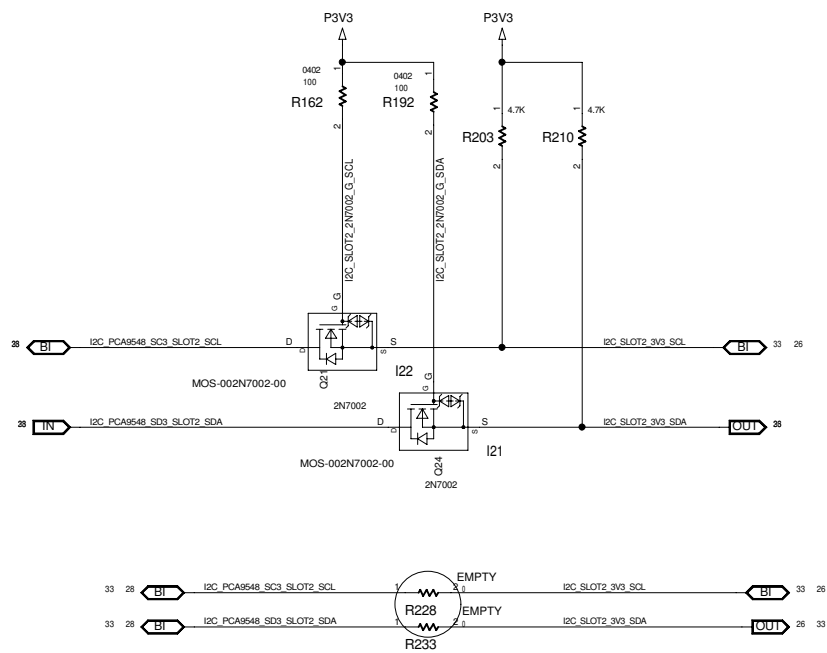
VCC(A): 0.8~5.5V
VCC(B): 2.2~5.5V

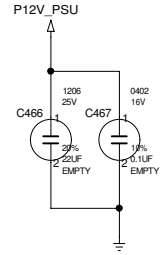
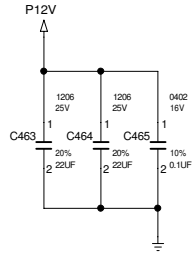
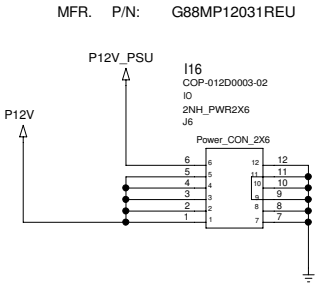


I2C DEBUG HEADER

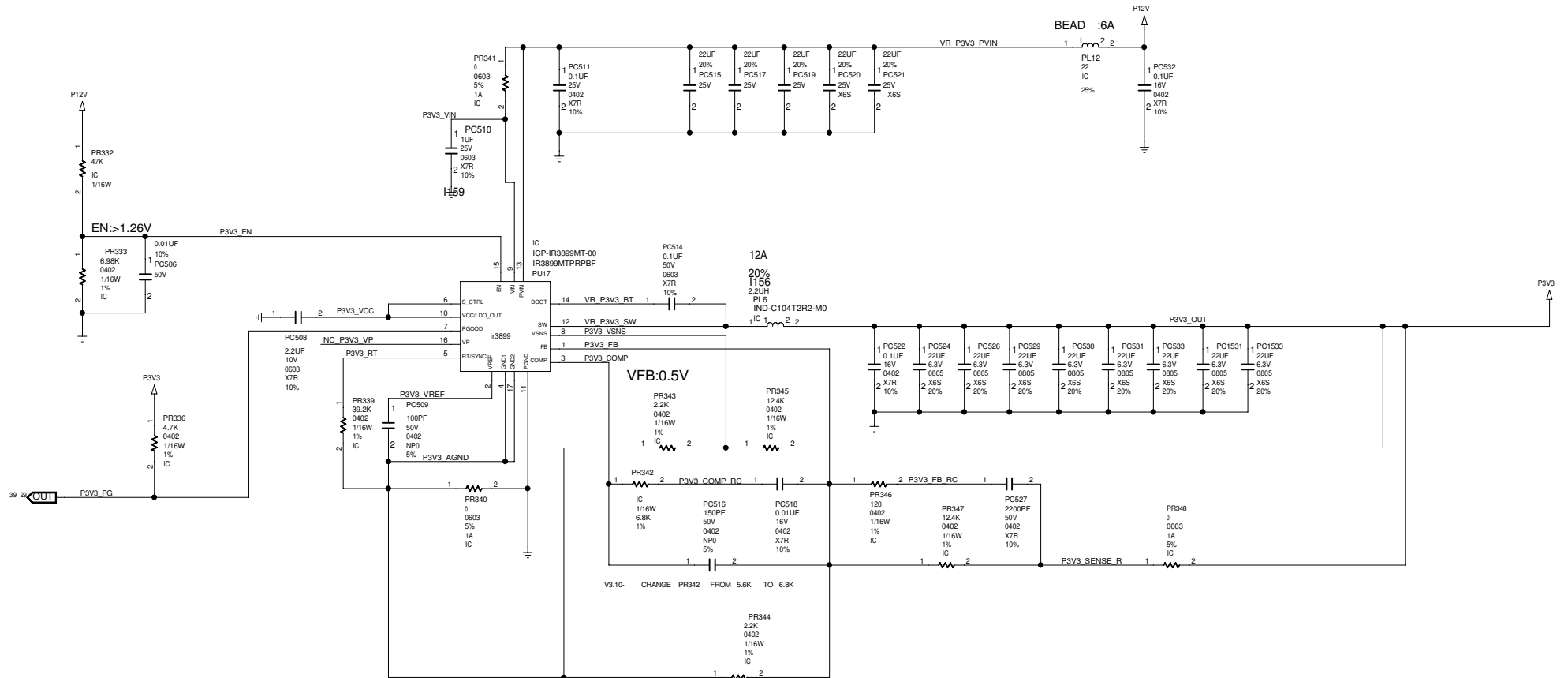








VR:P3V3



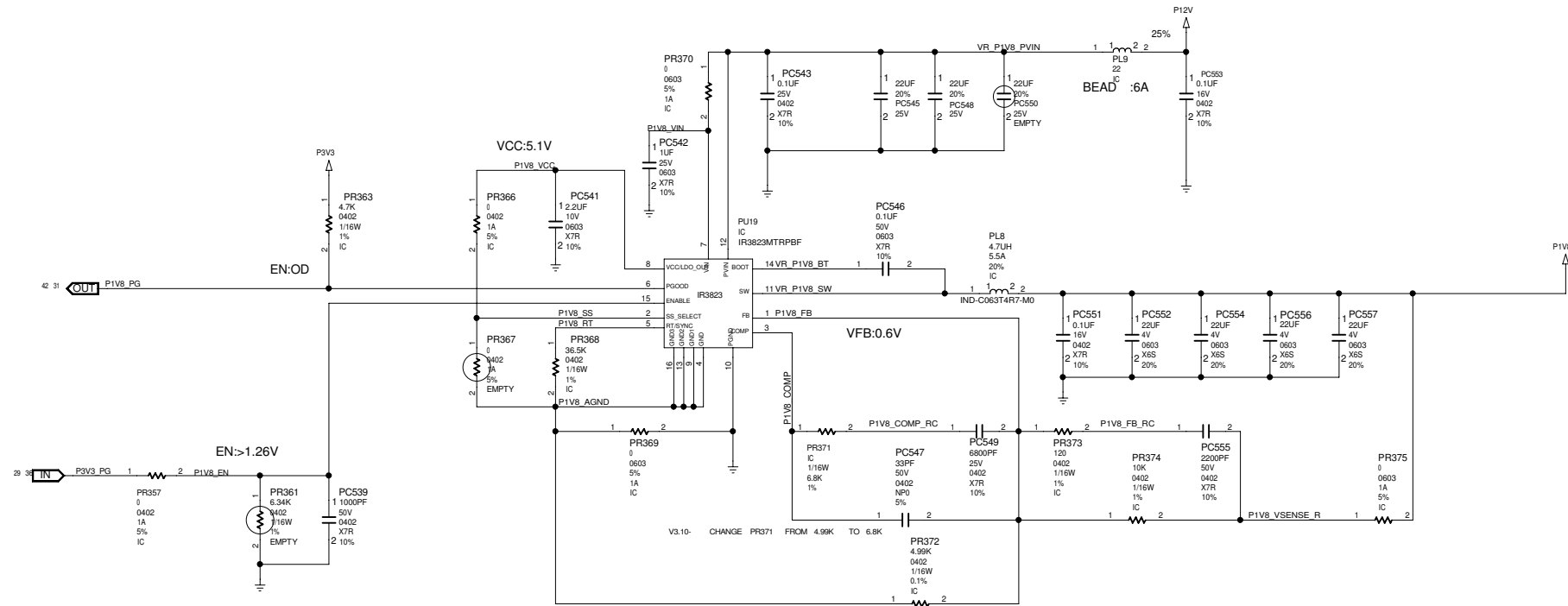
P12V TO P3V3 (AC:±5%)
TDC :6A
IMAX :6A
FSW :605KHZ
SOLUTION :IR3899 (9A POL)

P3V3



DEPARTMENT	DESIGNER NAME	PROJCT <ZT_PROJ>	DOCUMENT NUMBER <ZT_NUMBER>	REV
	REVIEWER NAME	SIZE C	DATE Fri Nov 23 13:38:46 2018	SHEET 36 OF 44

VR:P1V8



P12V TO P1V8 (AC:±5%)
TDC :1A
IMAX :1A
FSW :648KHZ
SOLUTION :IR3823 (3A POL)



DEPARTMENT	DESIGNER NAME	PROJECT	DOCUMENT NUMBER	REV
	REVIEWER NAME	<ZT_PROJ>	<ZT_NUMBER>	<ZT_REV>
SIZE	C	DATE	Fri Nov 23 13:38:46 2018	SHEET 39 OF 44

E

E

D

D

C

C

B

B

A

A

UNTITLED



DEPARTMENT

DESIGNER	
----------	--

NAME _____

PROJCT	
--------	--

<ZT_PROJ>

DOCUMENT NUMBER

<ZT_NUMBER>

REV

<ZT_REV>

REVIEWER

NAME

SIZE	C
------	---

C	D
---	---

C	DATE
---	------

ET

Thu J

ul	C
----	---

05	11
----	----

:17:23

2

2018

SHEE

ET 40

7

6

5

4

3

2

1

E

E

D

D

C

C

B

B

A

A

UNTITLED



DEPARTMENT

DESIGNER	
----------	--

NAME _____

PROJCET

PROJECT
— <ZT_PROJ>

DOCUMENT NUMBER

<ZT_NUMBER>

REV

REV>

REVIEWER

NAME

SIZE	C
------	---

C	D
---	---

C	DATE
---	------

ET

 Thu | Ju |

05

11:1

7:24

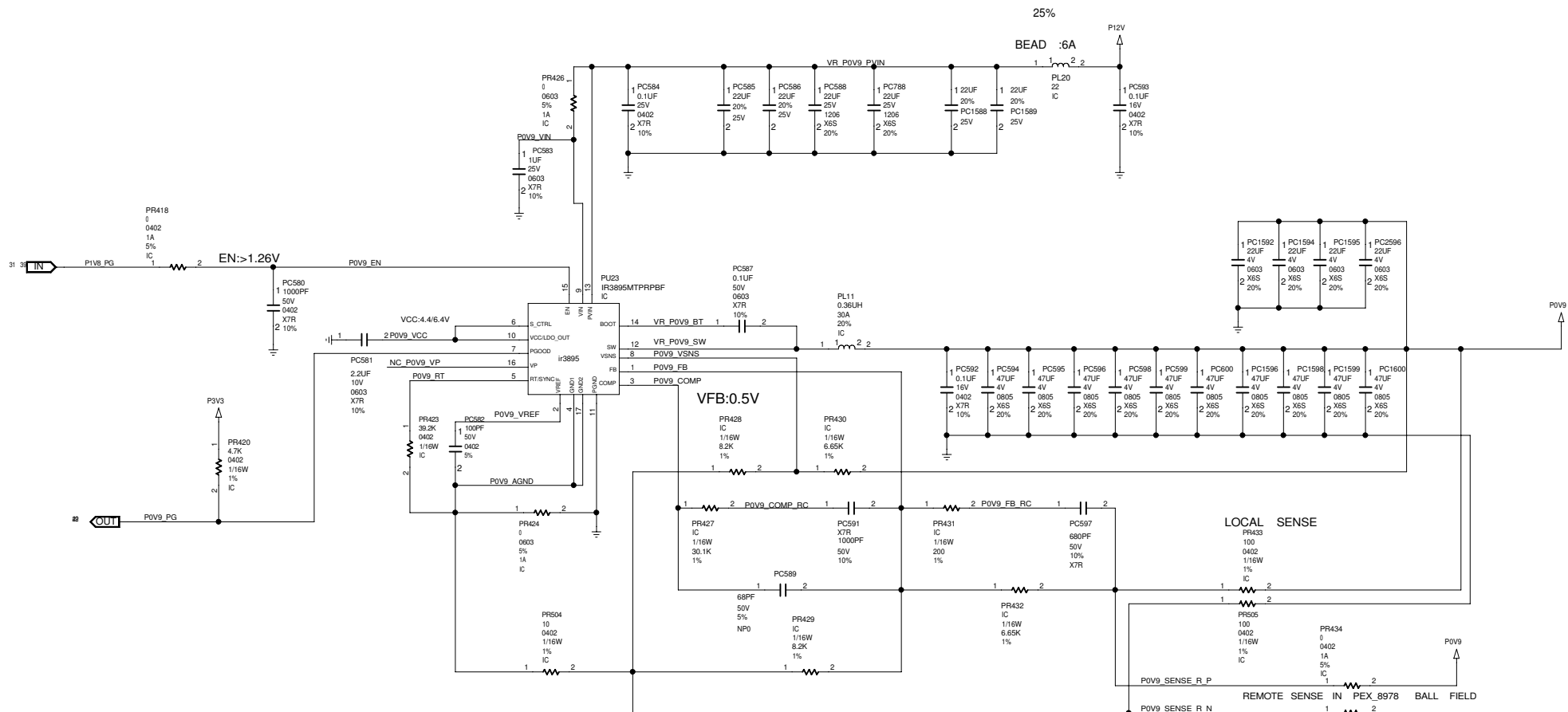
201

8	SH
---	----

SHEET 4

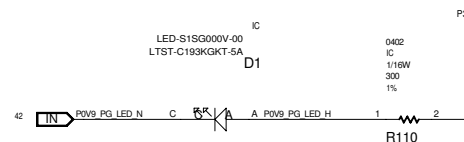
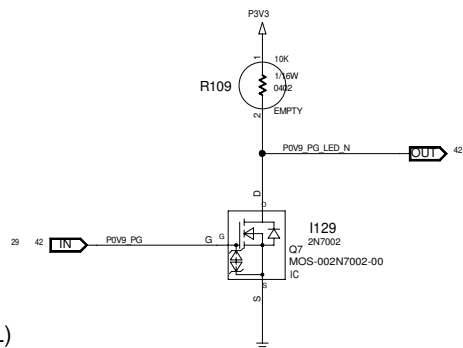
1 OF

VR:P0V9



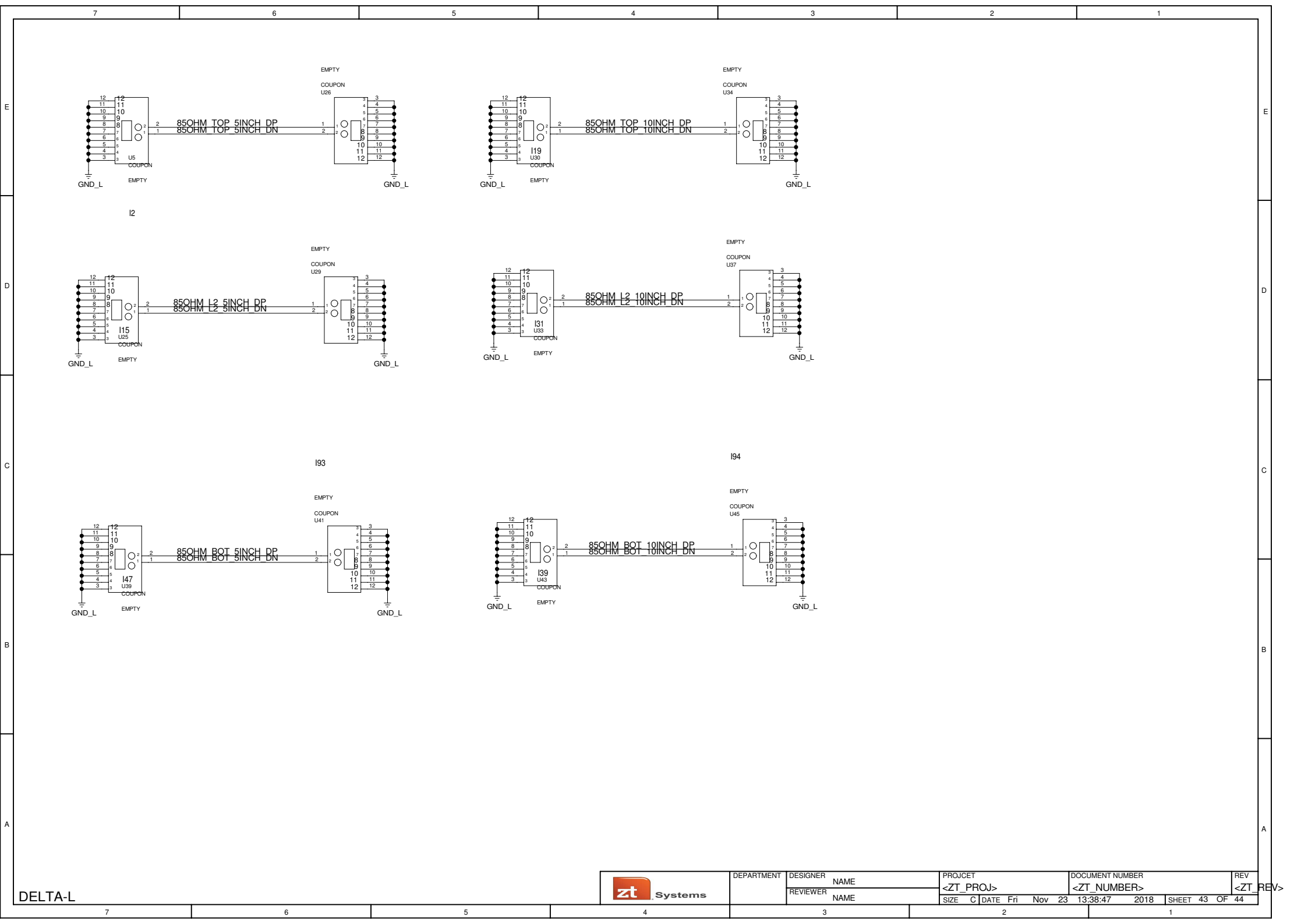
V3.10-	CHANGE	PC597	FROM	2200PF	TO	680PF	
	CHANGE	PC591	FROM	6800PF	TO	1000PF	
	CHANGE	PR431	FROM	120OHM	TO	200OHM	
	CHANGE	PR432	FROM	10.2K	TO	6.65K	
	CHANGE	PR430	FROM	10K	TO	6.65K	
	CHANGE	PR428	AND	PR429	FROM	12.4K	TO 8.2K
	CHANGE	PR427	FROM	6.19K	TO	30.1K	
	CHANGE	PC589	FROM	150PF	TO	68PF	

ROUTE	DIFFERENTIAL	PIAR	WIDTH	10MILS,SPACING	5 MILS
-------	--------------	------	-------	----------------	--------

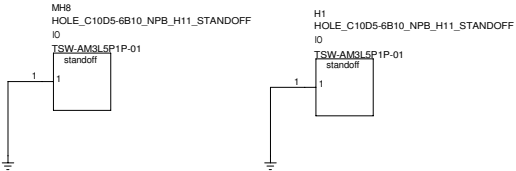


P12V TO P0V9 (AC:±5%)
TDC :13.6A
IMAX :16A
FSW :605KHZ
SOLUTION :IR3895 (16A POL)

P0V9

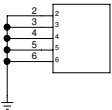


V3.9- CHANGE SCREW COLOR



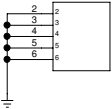
TEMP_C10D4XC10D6.5_L5

EMPTY
C10D4XC10D6.5_5V
MH9



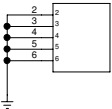
TEMP_C10D4XC10D6.5_L5

EMPTY
C10D4XC10D6.5_5V
MH10



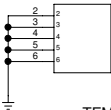
TEMP_C10D4XC10D6.5_L5

EMPTY
C10D4XC10D6.5_5V
MH11



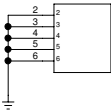
TEMP_C10D4XC10D6.5_L5

EMPTY
C10D4XC10D6.5_5V
MH5



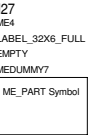
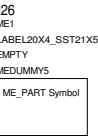
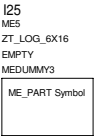
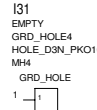
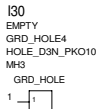
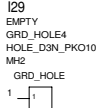
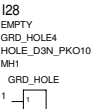
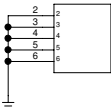
TEMP_C10D4XC10D6.5_L5

EMPTY
C10D4XC10D6.5_5V
MH6



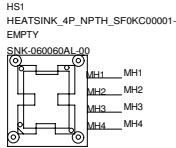
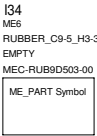
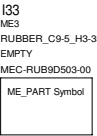
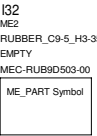
TEMP_C10D4XC10D6.5_L5

EMPTY
C10D4XC10D6.5_5V
MH7



RUBBER

HEATSINK



SCREW HOLE



DEPARTMENT	DESIGNER	NAME	PROJCT	DOCUMENT NUMBER	REV
	REVIEWER	NAME	<ZT_PROJ>	<ZT_NUMBER>	<ZT_REV>
			SIZE	C	DATE
			Fri	Nov	23
			13:38:46	2018	SHEET
			44	OF	44